Contents

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	30	V
V_{DS}	Drain-source voltage @ T_{jmax}	35	V
V_{GS}	Gate-source voltage	±20	V
I_D(1)	Drain current (continuous) at T_C = 25 °C	48	A
I_D	Drain current (continuous) at T_C = 100 °C	42.8	A
I_{DM}(2)	Drain current (pulsed)	192	A
P_{TOT}	Total dissipation at T_C = 25 °C	60	W
	Derating factor	0.4	W/°C
E_{AS}(3)	Single pulse avalanche energy	160	mJ
T_J	Operating junction temperature range	-55 to 175	°C
T_{stg}	Storage temperature range		

Notes:

(1)Limited by wire bonding.

(2)Pulse width limited by safe operating area.

(3)Starting T_j = 25 °C, I_D = 24 A, V_{DD} = 12 V.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	2.5	°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient	100	

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 4: On/off-state

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS}= 0, I_D = 250 µA	30			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 30 V			1	µA
		V_{GS} = 0 V, V_{DS} = 30 V; T_C = 125 °C (1)			10	µA
I_{GSS}	Gate body leakage current	V_{DS} = 0 V, V_{GS} = ±20 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	1	1.8	3	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 24 A		0.0076	0.0084	Ω
		V_{GS} = 5 V, I_D = 24 A		0.0092	0.0114	Ω

Notes:

(1)Defined by design, not subject to production test.

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0 V	-	1350	1620	pF
C_{oss}	Output capacitance		-	265	318	pF
C_{rss}	Reverse transfer capacitance		-	32	38	pF
Q_g	Total gate charge	V_{DD} = 15 V, I_D = 48 A, V_{GS}= 5 V, (see *Figure 14: "Test circuit for gate charge behavior"*)	-	8.8	12.3	nC
Q_{gs}	Gate-source charge		-	4.7	6.6	nC
Q_{gd}	Gate-drain charge		-	2.2	3.1	nC
R_G	Intrinsic gate resistance	f = 1 MHz, I_D=0 A	-	1.1	1.3	Ω

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD}= 10 V, I_D = 24 A, R_G = 4.7 Ω, V_{GS} = 10 V (see *Figure 13: "Test circuit for resistive load switching times"* and *Figure 18: "Switching time waveform"*)	-	6	-	ns
t_r	Rise time		-	33	-	ns
$t_{d(off)}$	Turn-off delay time		-	19	-	ns
t_f	Fall time		-	4.2	-	ns

Table 7: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		48	A
I_{SDM}(1)	Source-drain current (pulsed)		-		192	A
V_{SD}(2)	Forward on voltage	I_{SD} = 24 A, V_{GS} = 0 V	-		1.1	V
t_{rr}	Reverse recovery time	I_{SD} = 48 A, di/dt = 100 A/µs, V_{DD} = 20 V, (see *Figure 15: "Test circuit for inductive load switching and diode recovery times"*)	-	25		ns
Q_{rr}	Reverse recovery charge		-	18.5		µC
I_{RRM}	Reverse recovery current		-	1.5		A

Notes:

(1)Pulse width limited by safe operating area

(2)Pulsed: pulse duration = 300 µs, duty cycle 1.5%

2.2 Electrical characteristics (curves)

Figure 2: Safe operating area

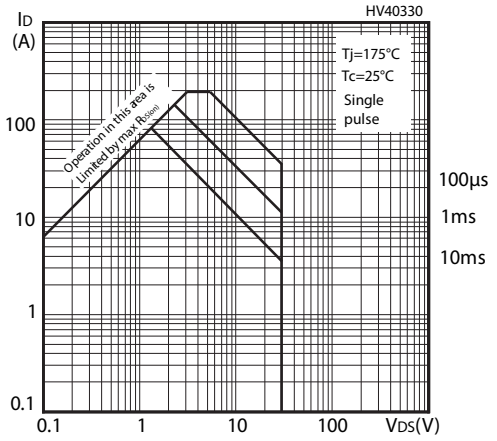


Figure 3: Thermal impedance

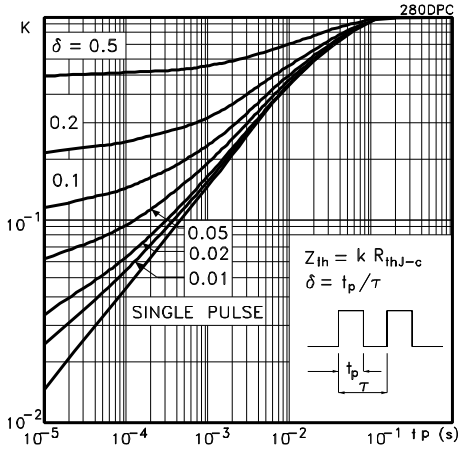


Figure 4: Output characteristics

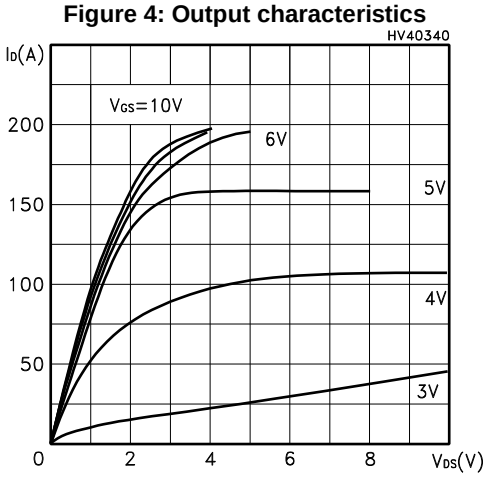


Figure 5: Transfer characteristics

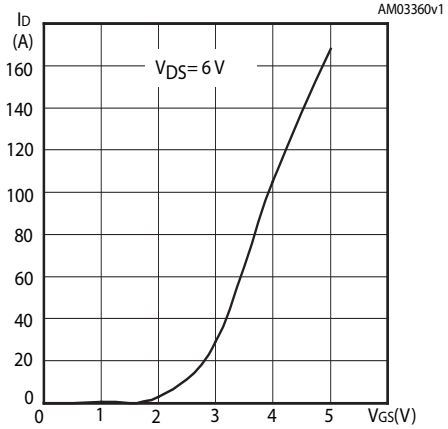


Figure 6: Gate charge vs gate-source voltage

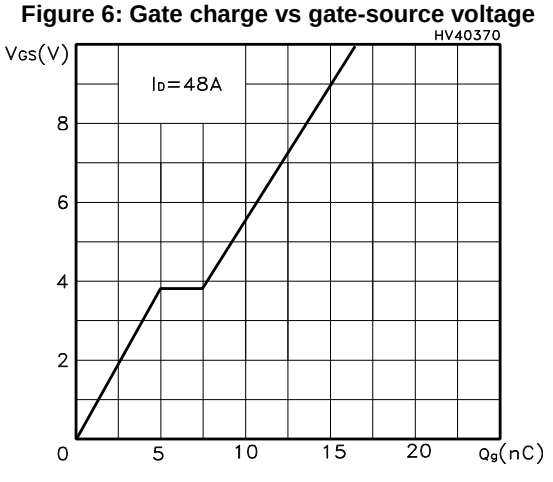


Figure 7: Static drain-source on-resistance

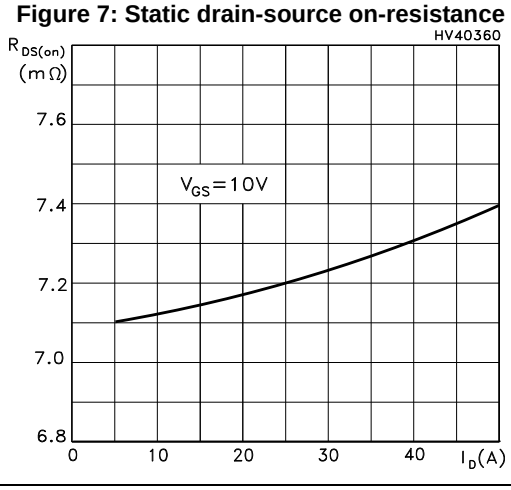


Figure 8: Capacitance variations

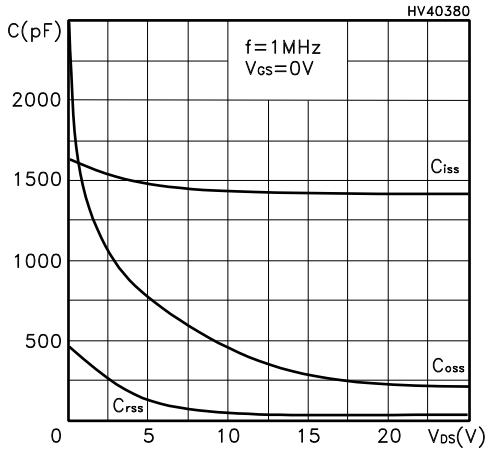


Figure 9: Normalized gate threshold voltage vs temperature

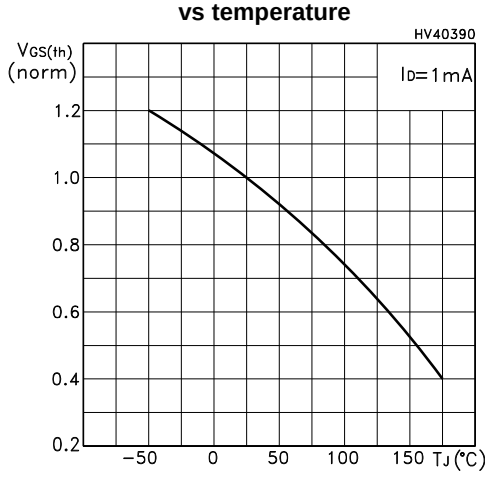


Figure 10: Normalized on-resistance vs temperature

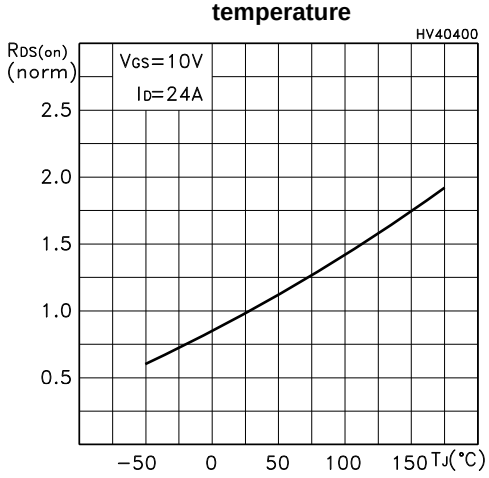


Figure 11: Normalized $V_{(BR)DSS}$ vs temperature

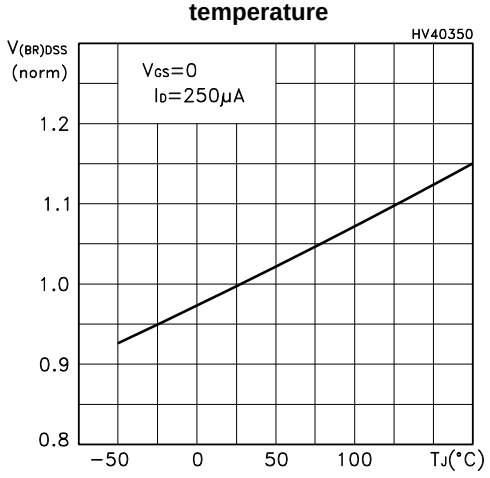
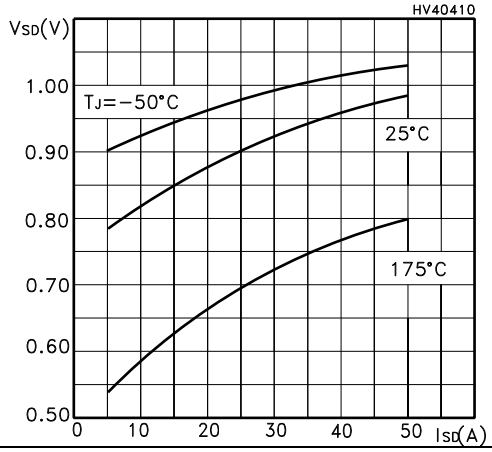


Figure 12: Source-drain diode forward characteristics



3 Test circuits

Figure 13: Test circuit for resistive load switching times

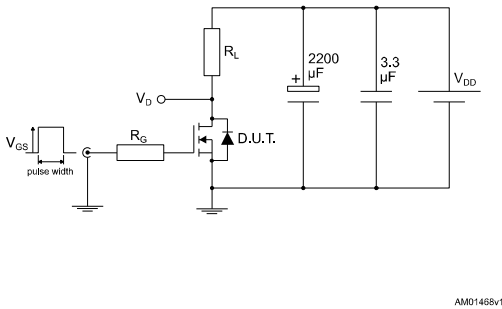


Figure 14: Test circuit for gate charge behavior

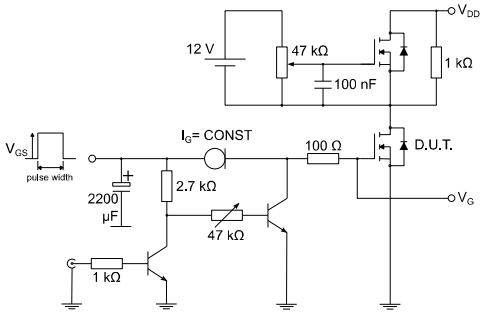


Figure 15: Test circuit for inductive load switching and diode recovery times

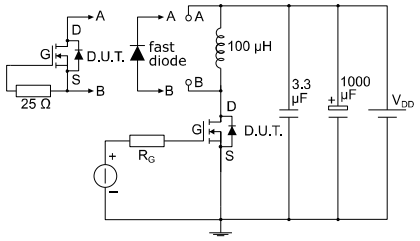


Figure 16: Unclamped inductive load test circuit

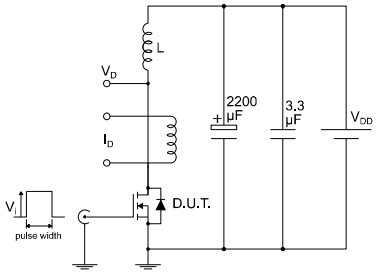


Figure 17: Unclamped inductive waveform

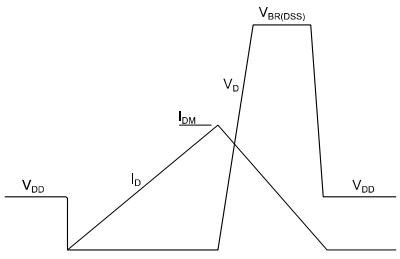
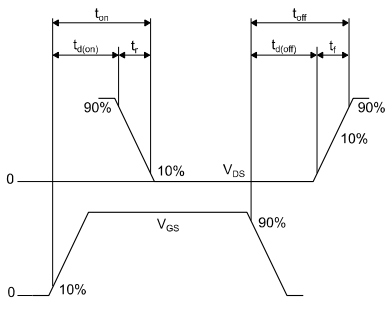


Figure 18: Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: ***www.st.com***. ECOPACK® is an ST trademark.

4.1 IPAK package information

Figure 19: IPAK (TO-251) type A package outline

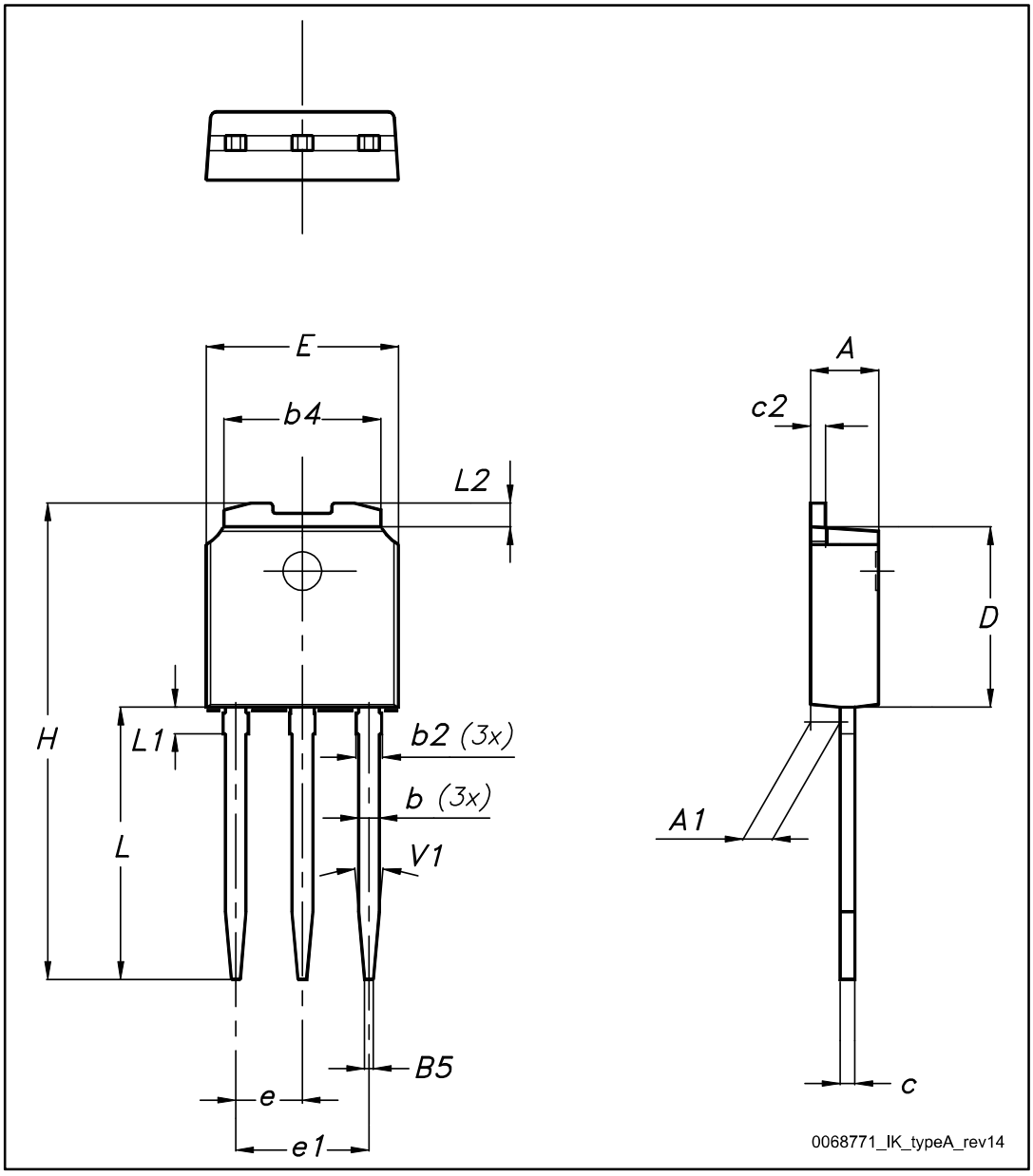


Table 8: IPAK (TO-251) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
09-Jun-2016	1	Initial release.

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